

PATENT

Attorney Reference Number 245-68071-01



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Paul et al.

Application No. 10/803,502

Filed: March 17, 2004

Confirmation No. 5691

For: METHOD FOR MAKING DEVICES
HAVING INTERMETALLIC
STRUCTURES AND INTERMETALLIC
DEVICES MADE THEREBY

Examiner: Unknown

Art Unit: 3729

Attorney Reference No. 245-68071-01

COMMISSIONER FOR PATENTS

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Attorney
for Applicant(s)Date Mailed April 8, 2005
TRANSMITTAL LETTER

Enclosed for filing in the application referenced above are the following:

- Information Disclosure Statement
- Form 1449 and references cited thereon
- The Director is hereby authorized to charge any additional fees that may be required, or credit over-payment, to Deposit Account No. 02-4550. A copy of this sheet is enclosed.
- Please return the enclosed postcard to confirm that the items listed above have been received.

Respectfully submitted,

KLARQUIST SPARKMAN, LLP

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INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. § 1.97(b)(3)

COMMISSIONER FOR PATENTS
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ALEXANDRIA, VA 22313-1450

Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

Copies of United States patents and United States published patent applications do not have to be provided to the Patent Office (37 C.F.R. 1.98(a)(2)(ii)). Copies of unpublished U.S. applications do not have to be provided, as long as the application is available on PAIR, as this requirement of 37 C.F.R. § 1.98(a)(2)(iii) has been waived by the United States Patent and Trademark Office pursuant to the Official Gazette Notice on October 19, 2004 (1287 OG 163). Applicants will provide copies of such patents or applications upon request.

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PATENT

Applicants filed this Information Disclosure Statement ("IDS") before the mailing date of a first Office action on the merits. As a result, no fee should be required to file this IDS. However, if the Patent Office determines that a fee is required for Applicants to file this IDS, please charge any such fees, or credit overpayment, to Deposit Account No. 02-4550. A **duplicate** copy of this Information Disclosure Statement is enclosed.

The filing of this IDS shall not be construed to be an admission that the information cited in the statement is, or is considered to be, prior art or otherwise material to patentability as defined in 37 C.F.R. §1.56.

Respectfully submitted,

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**INFORMATION DISCLOSURE STATEMENT
BY APPLICANT**

Attorney Docket Number	245-68071-01
Application Number	10/803,502
Filing Date	March 17, 2004
First Named Inventor	Paul
Art Unit	3729
Examiner Name	Unknown

U.S. PATENT DOCUMENTS

NOTE: If this application was filed after June 30, 2003, copies of United States patents and United States published patent applications do not have to be provided to the Patent Office. This requirement of 37 C.F.R. § 1.98(a)(2)(i) has been waived by the United States Patent and Trademark Office pursuant to the Official Gazette Notice on August 5, 2003 (1276 OG 55).

Examiner's Initials*	Cite No. (optional)	Number	Publication Date	Name of Applicant or Patentee
/N.D./		4,647,748	3/1987	Glassman
		4,875,619	10/1989	Anderson et al.
		5,087,930	2/1992	Roy et al.
		5,469,264	11/1995	Shigemori
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EXAMINER SIGNATURE:	/Nicholas D'aniello/	DATE CONSIDERED:	05/27/2008
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* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Attorney Docket Number	245-68071-01
		Application Number	10/803,502
		Filing Date	March 17, 2004
		First Named Inventor	Paul
		Art Unit	3729
		Examiner Name	Unknown
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Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS	
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		Esposito, "Fluid Power with Applications," <i>Prentice Hall</i> , pages 380-381, 1988.	
		Goldberg, "Narrow Channel Forced Air Heat Sink," <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> , Vol. CHMT-7 No. 1, pages 154-159, March 1984.	
		Haas et al., "Fabrication and Performance of MMW and SMMW Platelet Horn Arrays," <i>Intl. J. Infrared and Millimeter Waves</i> , Vol. 14(11), pages 2289-2293, 1993.	
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		Humphston et al., "Principles of Soldering and Brazing, 4.4.2. Diffusion Soldering and Brazing," <i>ASM International</i> , pages 128-132, 143, 1993.	
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		Khan et al., "Transient liquid phase diffusion bonding and associated recrystallization phenomenon when joining ODS ferritic superalloys," <i>J. of Mat. Sci</i> , Vol. 31, pages 2937-2943, June 1996.	

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